

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2123	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 16:36
L2	3192	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 16:36
L3	1772	L1 not L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 16:36
S1	3	((wire near3 (conductive adj resin)) near5 bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 21:31
S2	3	((wire near3 (conductive adj resin)) with bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 21:31
S3	4	((wire WITH (conductive adj resin)) SAME bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 21:32
S4	11	((wire SAME (conductive adj resin)) SAME bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 21:32
S5	1	"6636334"	USPAT	OR	OFF	2004/08/04 13:10
S6	3	"6333566"	USPAT	OR	OFF	2004/08/04 13:11

S7	588	257/790.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S8	3302	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S9	785	257/788.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S10	1916	257/723.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S11	1516	257/686.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S12	476	257/685.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:39
S13	3566	257/666.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40
S14	784	257/730.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40
S15	1931	257/774.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40
S16	623	257/680.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40

S17	657	358/434.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40
S18	599	358/482.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:40
S19	105	358/513.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:41
S20	77	257/480.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:41
S21	921	257/696.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:41
S22	1274	257/693.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:42
S23	15886	"6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:56
S24	13799	("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:57

S25	9041	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:58
S26	4276	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/04 13:59
S27	2945	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 13:54
S28	516	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)) and (adhesive near3 (sheet or tape))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 13:46

S33	12	((wire SAME (conductive adj resin)) SAME bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 13:40
S34	561	(((((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)) and (adhesive near3 (sheet or tape))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 13:49
S35	3192	(((((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 15:24
S36	695	(((((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	US-PGPUB	OR	OFF	2005/01/07 13:55

S37	2377	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	USPAT	OR	OFF	2005/01/07 13:59
S38	120	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 14:09
S39	1	("5696666").PN.	USPAT	OR	OFF	2005/01/07 14:10
S40	1	("5138433").PN.	USPAT	OR	OFF	2005/01/07 14:10
S41	1	("6122176").PN.	USPAT	OR	OFF	2005/01/07 14:10
S42	1	("6122172").PN.	USPAT	OR	OFF	2005/01/07 14:11
S43	1	("6122171").PN.	USPAT	OR	OFF	2005/01/07 14:11
S44	1	("3536964").PN.	USPAT	OR	OFF	2005/01/07 14:11
S45	1	("5798564").PN.	USPAT	OR	OFF	2005/01/07 14:11
S46	1	("5422513").PN.	USPAT	OR	OFF	2005/01/07 14:11
S47	1	("5280192").PN.	USPAT	OR	OFF	2005/01/07 14:12
S48	1	("5241456").PN.	USPAT	OR	OFF	2005/01/07 14:12
S49	1	("6153928").PN.	USPAT	OR	OFF	2005/01/07 14:12
S50	1	("5811879").PN.	USPAT	OR	OFF	2005/01/07 14:12
S51	1	("5384689").PN.	USPAT	OR	OFF	2005/01/07 14:12
S52	1	("4989063").PN.	USPAT	OR	OFF	2005/01/07 14:12
S53	1	("5723907").PN.	USPAT	OR	OFF	2005/01/07 14:13
S54	1	("5986339").PN.	USPAT	OR	OFF	2005/01/07 14:13
S55	1	("4996582").PN.	USPAT	OR	OFF	2005/01/07 14:13
S56	1	("4996587").PN.	USPAT	OR	OFF	2005/01/07 14:14
S57	1	("6013948").PN.	USPAT	OR	OFF	2005/01/07 14:14

S58	1	("5723900").PN.	USPAT	OR	OFF	2005/01/07 14:14
S59	1	("5744862").PN.	USPAT	OR	OFF	2005/01/07 14:14
S60	1	("5939585").PN.	USPAT	OR	OFF	2005/01/07 14:14
S61	1	("5763939").PN.	USPAT	OR	OFF	2005/01/07 14:14
S62	23	S39 S40 S41 S42 S43 S44 S45 S46 S47 S48 S49 S50 S51 S52 S53 S54 S55 S56 S57 S58 S59 S60 S61	USPAT	OR	OFF	2005/01/07 14:15
S63	2123	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 15:24
S64	3192	((("6636334" or "6333566" or 257/790.ccls. or 257/787.ccls. or 257/788.ccls. or 257/723.ccls. or 257/686.ccls. or 257/685.ccls. or 257/666.ccls. or 257/730.ccls. or 257/774.ccls. or 257/680.ccls. or 358/434.ccls. or 358/482.ccls. or 358/513.ccls. or 257/480.ccls. or 257/696.ccls. or 257/693.ccls.) and (semiconductor or ic or chip or die or (integrated adj circuit))) and (bonding or wire or wiring)) and (via or (through adj hole))) and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/07 15:24